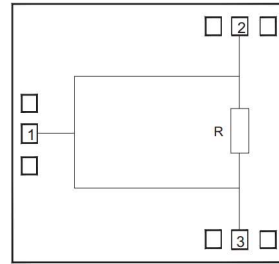


Performance

- Frequency: 3.0~9.0GHz
- Insertion loss: 0.8dB
- Chip size: 1.10*1.00*0.1mm

Function Diagram

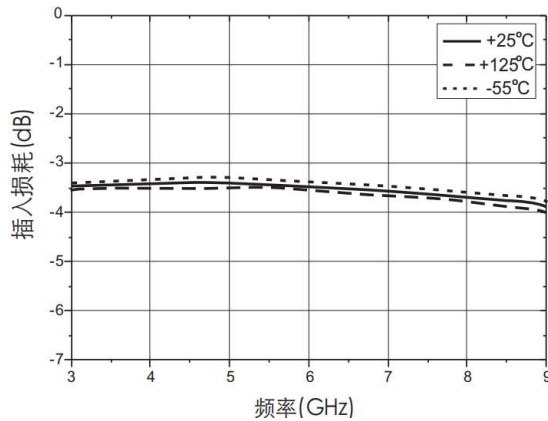


Electrical Specifications (Ta=+25°C, 50Ω system)

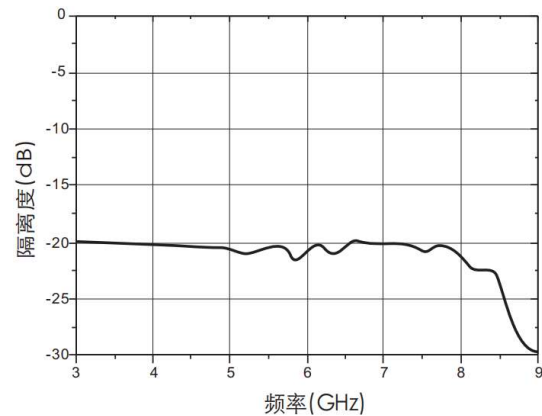
Parameter	Min	Typical	Max	Unit
Frequency Range	3.0~9.0			GHz
Insertion Loss	-	0.8	1.2	dB
Insertion Loss Ripple	-	±0.4	-	dB
Isolation	18	22	-	dB
Input Return Loss	15	20	-	dB
Output Return Loss	17	22	-	dB

Test Curves

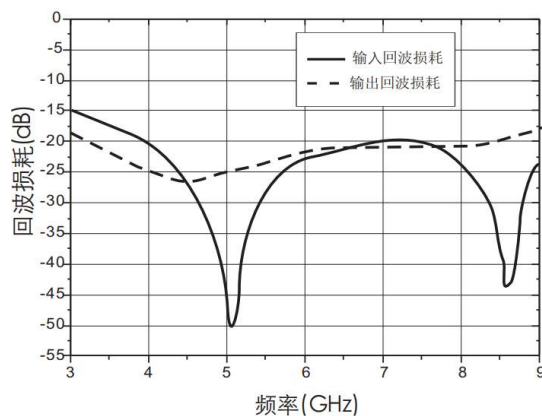
Insertion loss vs. Freq



Isolation vs. Freq



Input/Output Return Loss vs. Freq



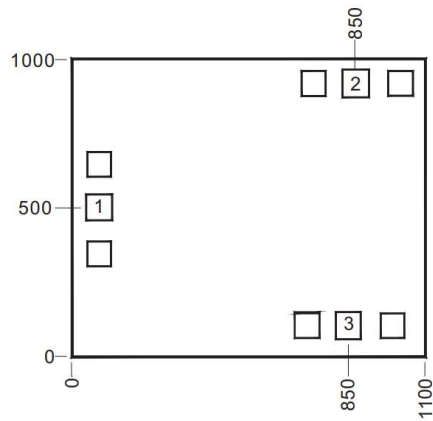
Absolute Max Ratings

RF Input Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static Protection (HBM)	Class 1B



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

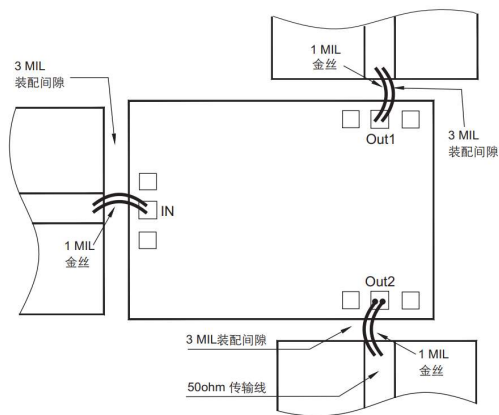
Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50 \mu\text{m}$

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	In	RF Input, 50ohm
2, 3	Out1, Out2	RF Output, 50ohm
	GND	Bottom must be grounded